

HyperScan

Paste thickness measurement

膠厚量測儀

Features

- Pure Granite base Stage
- Non-contact measurement
- Semiconductor Laser sensor
- Measurement for paste and Die Thickness
- High accuracy of 0.3um resolution
- 350 X 350 mm measurement area
- Effective measurement height 600um



HyperScan-WF

Wafer Thickness measurement 晶元厚度量測儀

- **Pure Granite base Stage**
- **High accuracy laser sensor head**
- **Wafer size capability: 6", 8", 12"**
- **Wafer thickness: 25um to 1500um**
- **Wafer Thickness measuring accuracy: +/- 2um**
- **Wafer type: Bare wafer and framed wafer**
- **Wafer with V-notch or flat**
- **To measure thickness of wafer and dicing tape**

